

SE630K

N-Channel Enhancement-Mode MOSFET

Revision: A

General Description

This type used advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of application

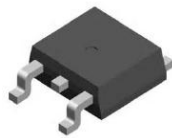
Features

For a single MOSFET

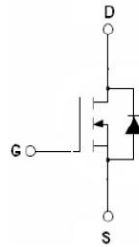
- $V_{DS} = 200V$
- $R_{DS(ON)} = 260m\Omega @ V_{GS} = 10V$

Pin configurations

See Diagram below



TO-252



Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	200	V
Gate-Source Voltage	V_{GS}	± 10	V
Drain Current	Continuous	11	A
	Pulsed	50	
Total Power Dissipation	@TA=25°C	2.5	W
Operating Junction Temperature Range	T_J	-55 to 175	°C

Thermal Resistance

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	-	50	°C/W

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Electrical Characteristics (T _J =25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS (Note 2)						
B _V DSS	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0 V	200			V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =30V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =10V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.5	1.9	2.5	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =3A	-	260	310	mΩ
g _{FS}	Forward Transconductance	V _{DS} =10V, I _D =11A	25			S
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		1155		pF
C _{oss}	Output Capacitance			260		pF
C _{rss}	Reverse Transfer Capacitance			95		pF
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =15V, I _D =8A		17.5		nC
Q _{gs}	Gate Source Charge			4.5		nC
Q _{gd}	Gate Drain Charge			2.5		nC
t _{d(on)}	Turn-On Delay Time	V _{GS} =5V, V _{DS} =15V, R _{GEN} =3Ω I _D =11A		10		ns
t _{d(off)}	Turn-Off Delay Time			40		ns
t _{d(r)}	Turn-On Rise Time			16		ns
t _{d(f)}	Turn-Off Fall Time			10.8		ns
Source-Drain Diode Characteristics						
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =24A			1.2	V
I _S	Diode Forward Current				11	A

Typical Characteristics

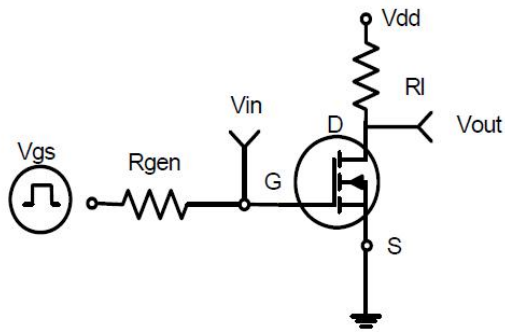


Figure 1: Switching Test Circuit

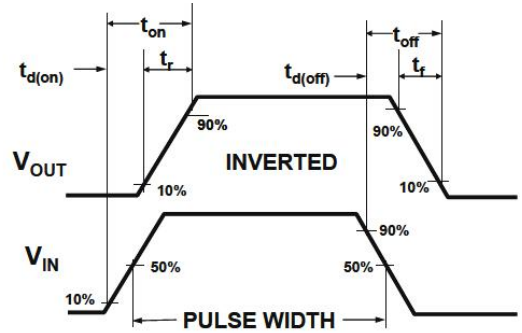


Figure 2: Switching Waveforms

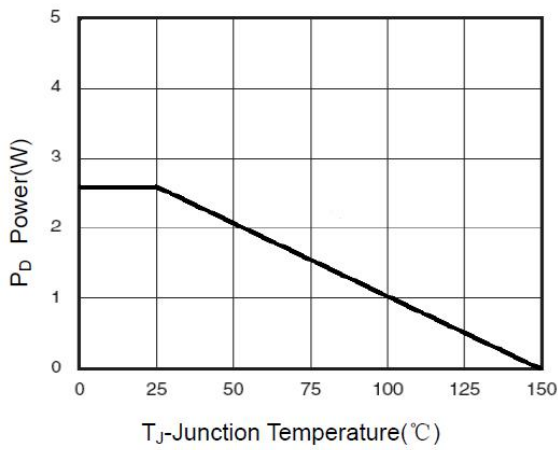


Figure 3 Power Dissipation

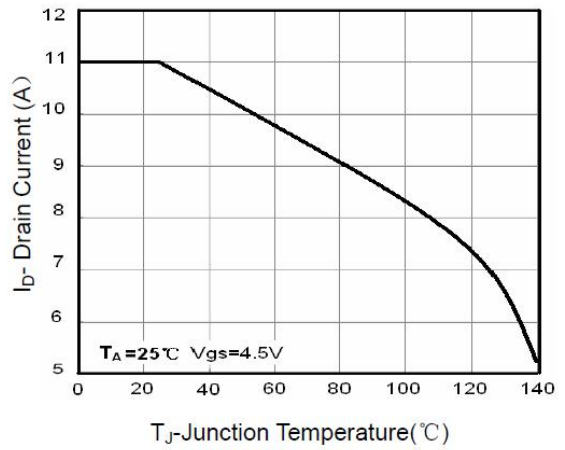


Figure 4 Drain Current

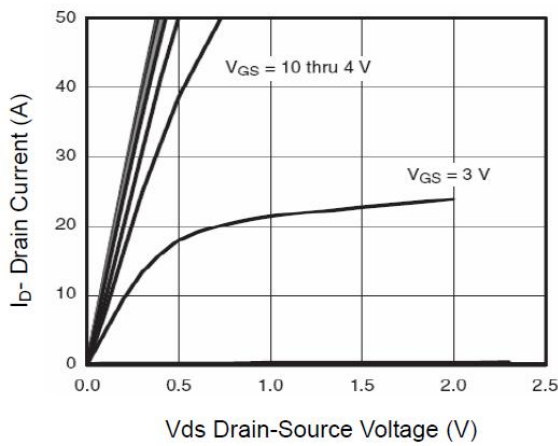


Figure 5 Output Characteristics

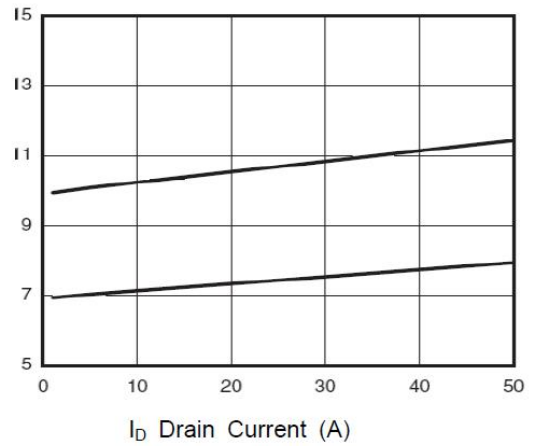


Figure 6 Drain-Source On-Resistance

Typical Characteristics

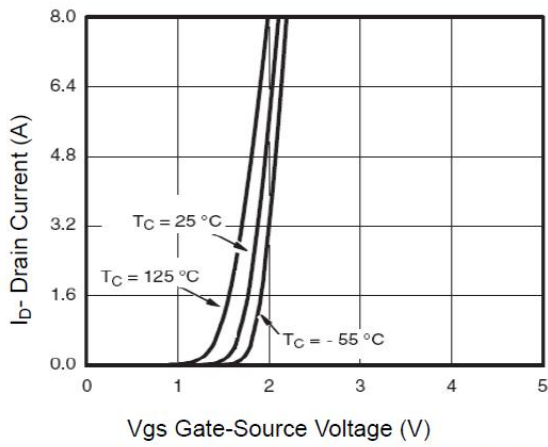


Figure 7 Transfer Characteristics

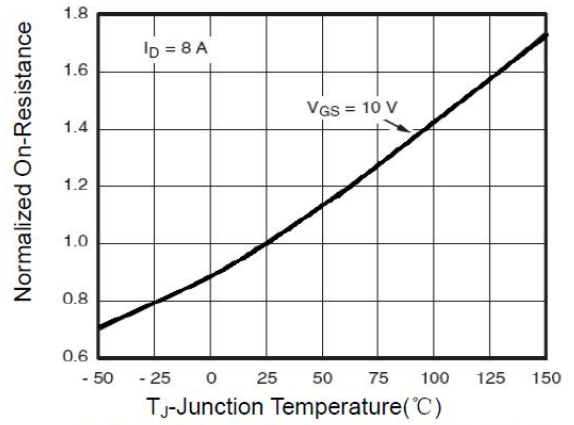


Figure 8 Drain-Source On-Resistance

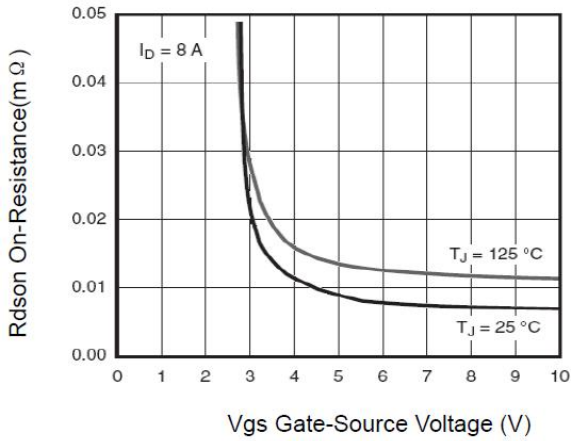


Figure 9 Rds(on) vs Vgs

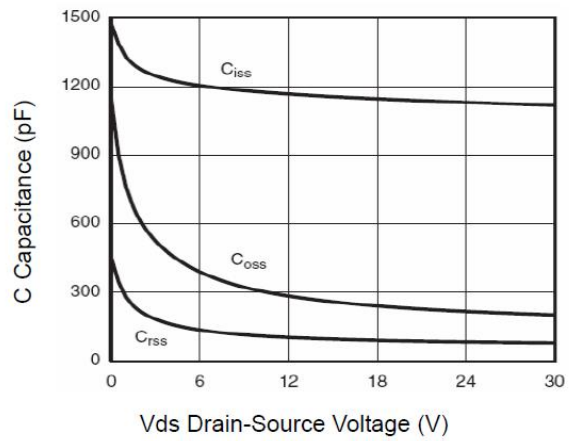


Figure 10 Capacitance vs Vds

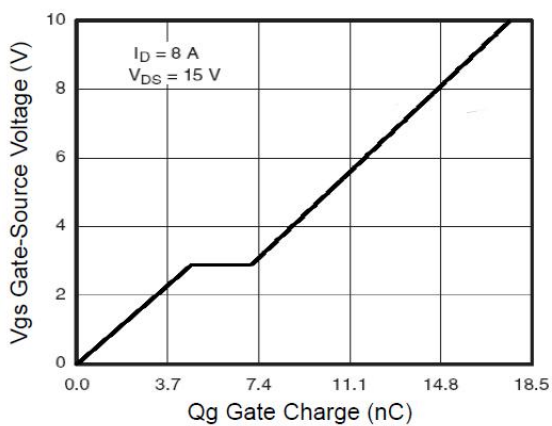


Figure 11 Gate Charge

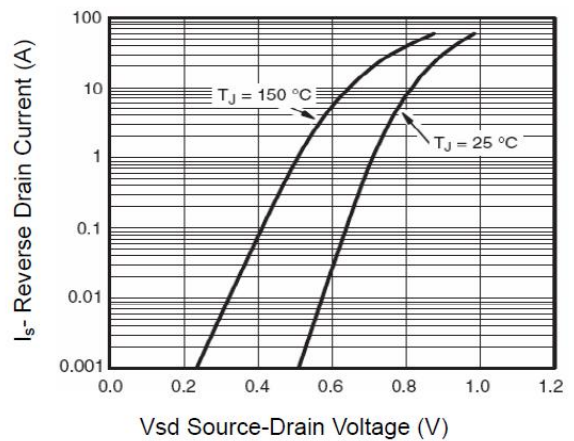
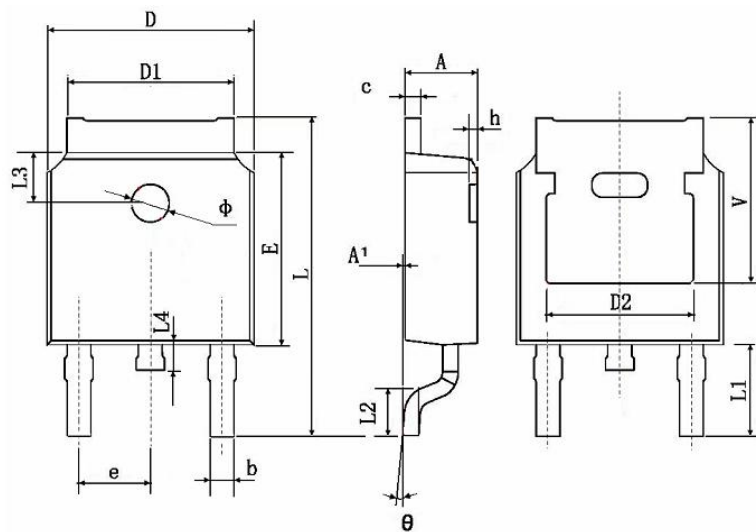


Figure 12 Source- Drain Diode Forward

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Package Outline Dimension

TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	0.483 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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